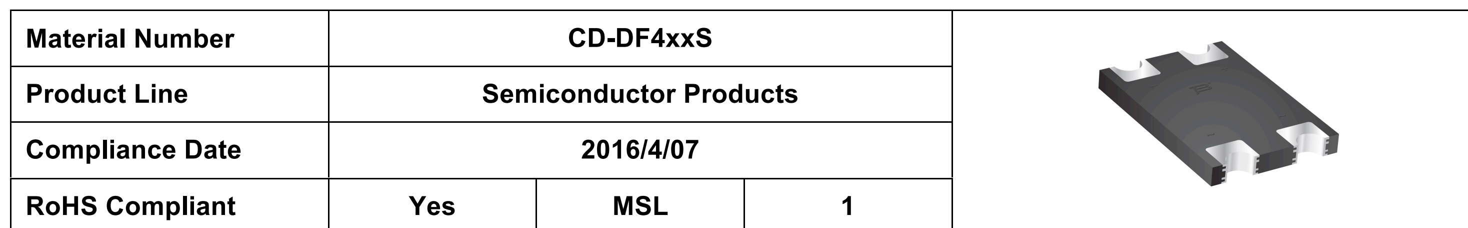
MATERIAL DECLARATION SHEET



Material Number	CD-DF4xxS		
Product Line	Semiconductor Products		
Compliance Date	2016/4/07		
RoHS Compliant	Yes	MSL	1

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Metal	173.7	Continuous filament glass fibers	65997-17-3	43	25.76	59.9
				Copper foil	7440-50-8	14	8.38	
				Non-Hazardous cured resin	Proprietary	43	25.76	
2	Epoxy	Plastic	73.7	Silicon Dioxide	7631-86-9	72.75	18.48	25.41
				Epoxy resin	9003-36-5	25.25	6.42	
				Carbon black	1333-86-4	2	0.51	
3	Solder Cream	Metal	10.4	Lead[2]	7439-92-1	88	3.16	3.59
				Tin	7440-31-5	10	0.36	
				Silver	7440-22-4	2	0.07	
4	Dice	Others	20.4	Silicon	7440-21-3	35.84	2.52	7.031
				Nickel	7440-02-0	0.71	0.05	
				Lead-containing glass[3]	7439-92-1	63.43	4.46	
				Gold	7440-57-5	0.02	0.001	
5	Solder wafer	Others	6	Lead[*2]	7439-92-1	92.51	1.914	2.069
				Tin	7440-31-5	4.98	0.103	
				Silver	7440-22-4	2.51	0.052	
6	Terminal Plating	Metal	5.8	Tin	7440-31-5	100	2.0	2.0
		Total weight	290					

This Document was updated on: 2016/4/07

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Important remarks:

1. **It is the responsibility of the user to verify they are accessing the latest version.**
2. **7(a) Lead in high melting temperature solders**
3. **7(c)-I Lead in a glass or ceramic matrix compound.**

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